

Accepted Manuscript

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PII: S1359-4311(17)36915-6
DOI: <https://doi.org/10.1016/j.applthermaleng.2018.02.051>
Reference: ATE 11833

To appear in: *Applied Thermal Engineering*

Received Date: 30 October 2017
Revised Date: 4 February 2018
Accepted Date: 13 February 2018



Please cite this article as: M. Chen, X. Sun, R.N. Christensen, I. Skavdahl, V. Utgikar, P. Sabharwall, Dynamic Behavior of a High-Temperature Printed Circuit Heat Exchanger: Numerical Modeling and Experimental Investigation, *Applied Thermal Engineering* (2018), doi: <https://doi.org/10.1016/j.applthermaleng.2018.02.051>

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Dynamic Behavior of a High-Temperature Printed Circuit Heat Exchanger: Numerical Modeling and Experimental Investigation

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Abstract

Printed circuit heat exchanger (PCHE) is one of the leading intermediate heat exchanger (IHX) candidates for the Very High Temperature Reactors due to its capability for high-temperature and high-pressure applications. An IHX serves to isolate the reactor primary system from electricity generation and process heat application plants, and therefore must be robust to maintain the entire system integrity during normal and off-normal conditions. Understanding the

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